

B520C - B560C

5.0A SURFACE MOUNT SCHOTTKY BARRIER RECTIFIER

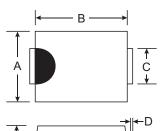
Features

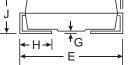
Guard Ring Die Construction for Transient Protection Ideally Suited for Automatic Assembly Low Power Loss, High Efficiency Surge Overload Rating to 175A Peak For Use in Low Voltage, High Frequency Inverters, Free Wheeling, and Polarity Protection Application Lead Free Finish/RoHS Compliant (Note 3)

Mechanical Data

Case: SMC

Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0 Moisture Sensitivity: Level 1 per J-STD-020C Terminals: Lead Free Plating (Matte Tin Finish). Solderable per MIL-STD-202, Method 208 3 Polarity: Cathode Band or Cathode Notch Marking Information: See Page 3 Ordering Information: See Page 3 Weight: 0.21 grams (approximate)





SMC					
Dim	Min	Max			
Α	5.59	6.22			
В	6.60	7.11			
С	2.75	3.18			
D	0.15	0.31			
Е	7.75	8.13			
G	0.10 0.20				
н	0.76	1.52			
J	2.00	2.62			
All Dimensions in mm					

Maximum Ratings and Electrical Characteristics @ T_A = 25°C unless otherwise specified

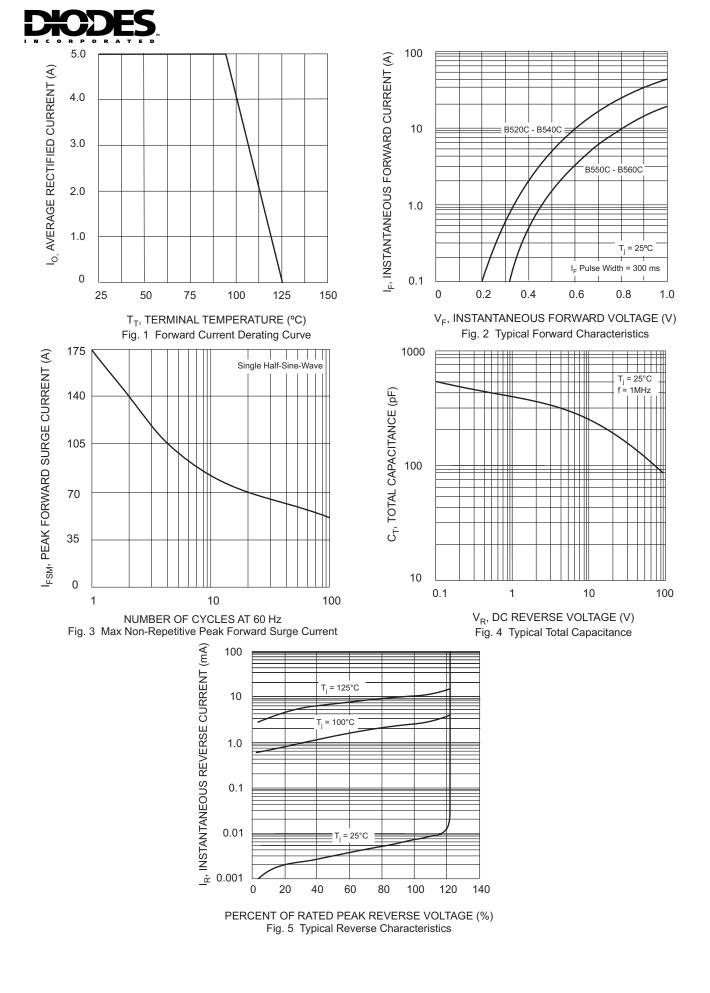
Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic		Symbol	B520C	B530C	B540C	B550C	B560C	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	20	30	40	50	60	v
RMS Reverse Voltage		V _{R(RMS)}	14	21	28	35	42	V
Average Rectified Output Current	@ $T_T = 90^{\circ}C$	lo	5.0				А	
Non-Repetitive Peak Forward Surge C half-sine-wave Superimposed on Rate		I _{FSM}	175			А		
Forward Voltage	@ I _F = 5.0A DC	V _{FM}	0.55 0.70			V		
Peak Reverse Current at Rated DC Blocking Voltage	@ $T_A = 25^{\circ}C$ @ $T_A = 100^{\circ}C$	I _{RM}	0.5 20			mA		
Typical Total Capacitance (Note 2)		Ст	300				pF	
Thermal Resistance, Junction to Terminal		R _{JT}	10				°C/W	
Thermal Resistance, Junction to Ambient (Note 1)		R _{JA}	50				°C/W	
Operating Temperature Range		Tj	-55 to +125				°C	
Storage Temperature Range		T _{STG}	-55 to +150			°C		

Notes: 1. Thermal Resistance: Junction to ambient, unit mounted on PC board with 8.0 mm² (0.033 mm thick) copper pads as heat sink.

2. Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.

3. RoHS revision 13.2.2003. High Temperature Solder Exemption Applied, see EU Directive Annex Note 7.



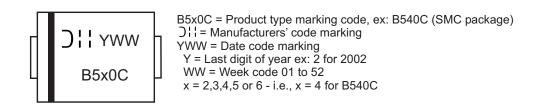


Ordering Information (Note 4)

Device	Packaging	Shipping
B520C-13-F	SMC	3000/Tape & Reel
B530C-13-F	SMC	3000/Tape & Reel
B540C-13-F	SMC	3000/Tape & Reel
B550C-13-F	SMC	3000/Tape & Reel
B560C-13-F	SMC	3000/Tape & Reel

Notes: 4. For Packaging Details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



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